IPC ASSOCIATION OF ELECTRONICS	© Copyright 2005.	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.			nder both	This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lower level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.									
1752-21.1		IPC Web Site for Information on IPC-1752 Standard Form Typhttp://www.ipc.org/IPC-175x Distribute				Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materi					ials and Mfg Information				
Supplier 1	Information														
Company name*			Company unique ID			ı	Unique ID Authority					Response Date*			
nsemi											2024-05-20				
Contact Nai	me		Title - Contact]	Phone - Contact*				Email - Contact*				
Product-Env-Stewards			Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com				
uthorized	Representative*	Title - Representative]	Phone - Representative*				Email - Representative*					
Product-Env-Stewards			Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com				
]	Requester Item Number M		em Number Mfr Item Name				Effective Da	te Version	ı	Manufacturing Site	W	eight*	UOM	Unit Type	
		NCV853 G	7MNADJR2	LDO			2024-05-20		1	MY1	25	1.39	mg	Each	
Manufact	turing Proccess Informa	ation													
Т	Terminal Plating / Grid Array Material Terminal Base Alloy			-STD-020 MS	L Rating	Rating Peak Process Body Temperature Max Time at Peak					re Num	ber of Reflow Cyc	les		
Matte Tin (Sn) - annealed CU Allo			Alloy 1				260 C 30		30	second	3				
Comments															
evel 1 - max	ximum time at peak temperat	ture during sol	dering is 10-3	0 seconds											
or more in	iformation regarding materia	l composition	please refer to	page 3											

RoHS Material Composition Declaration			Declaration Type *	Detail	ed					
Directive 2015/863/EU amending RoHS Directive 2011/65/EU		ium (Cr6+), Polybrominated Biphenyls (PB)	erial for Cadmium and quantity limit of 0.1% b B), Polybrominated Diphenyl Ethers (PBDE), a							
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on informationprovided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier have provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part, the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusivesource of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form. In the absence of such written agreement, the warranty rights and/or remedies of Supplier's Standard Terms and Conditions of Sale applicable to such part shall apply.										
RoHS Declaration * 1 - Item	(s) does not contain RoHS restricted substar	nces per the definition above	Supplier A	cceptance *	Accepted					
Exemption: If the declared item does not contain RoHS restricted substances per the definition above except for defined RoHS exemptions, then select the corresponding response in the RoHS Declaration above and choose all applicable exemptions.										
Exemption List Version	EL-2011/534/EU									
Declaration Signature										
		e "Accepted" on the Supplier Acceptance	drop-down. This will display the signature a	rea. Digitally sign t	the declaration (if required by the					

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	1.42	mg	Supplier	Silicon (Si)	7440-21-3		1.42	mg
Die Attach Epoxy	0.32	mg	Supplier	Silver (Ag)	7440-22-4		0.2944	mg
			Supplier	Phenolic Resin-2	54208-63-8		0.0256	mg
Lead Frame	10.59	mg	Supplier	Silver (Ag)	7440-22-4		0.1059	mg
			Supplier	Tin (Sn)	7440-31-5		0.0265	mg
			Supplier	Zinc (Zn)	7440-66-6		0.0233	mg
			Supplier	Chromium (Cr)	7440-47-3		0.0265	mg
			Supplier	Copper (Cu)	7440-50-8		10.4079	mg
Mold Compound-Black	12.39	mg	Supplier	Epoxy and Phenolic Resin	40216-08-8		0.9912	mg
			Supplier	Carbon Black (C)	1333-86-4		0.062	mg
			Supplier	Aluminum Hydroxide (Al(OH)3)	21645-51-2		0.2478	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		10.7174	mg
			Supplier	Phenolic Resin (Novolac)	9003-35-4		0.3717	mg
Plating	0.56	mg	Supplier	Tin (Sn)	7440-31-5		0.56	mg
Wire Bond - Au	0.11	mg	Supplier	Gold (Au)	7440-57-5		0.11	mg